



Invitation Letter

April 21, 2026

To:

Minbo Wang
Hunan University Of Science And Technology, China
wangminbo@hnust.edu.cn

Dear Minbo Wang,

On behalf of the Organizing Committee of the 32nd International Conference on Computational & Experimental Engineering and Sciences (ICCES2026), we are pleased to formally invite you to attend ICCES2026, which will be held in Hong Kong SAR, China, from August 7 to 12, 2026.,

We are pleased to inform you that your paper entitled "*Formation mechanism of metastable microstructure in laser additive non-equilibrium solidified aluminum alloys*" (ID: 14865), has been accepted for oral presentation at the conference. Please complete your registration at your earliest convenience: www.iccesconf.org/registration.

We also encourage you to finalize your travel arrangements well in advance to ensure your full participation not only in presenting your paper, but also in engaging in the insightful technical discussions throughout the conference.

Should you require any further information, please feel free to contact the ICCES Secretariat

Sincerely,

Zuankai Wang
Conference Chair, ICCES2026
Department of Mechanical Engineering
The Hong Kong Polytechnic University
Hong Kong SAR, China



International Conference on Computational & Experimental Engineering and Sciences

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